



National Standards Authority of Ireland
Údarás um Chaighdeán Náisiúnta na hÉireann

IRISH STANDARD

I.S. EN 60749-37:2008

ICS 31.080.01

**SEMICONDUCTOR DEVICES -
MECHANICAL AND CLIMATIC TEST
METHODS -- PART 37: BOARD LEVEL
DROP TEST METHOD USING AN
ACCELEROMETER (IEC 60749-37:2008
(EQV))**

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EUROPEAN STANDARD

EN 60749-37

NORME EUROPÉENNE

EUROPÄISCHE NORM

April 2008

ICS 31.080.01

English version

**Semiconductor devices -
Mechanical and climatic test methods -
Part 37: Board level drop test method using an accelerometer
(IEC 60749-37:2008)**

Dispositifs à semiconducteurs -
Méthodes d'essais mécaniques
et climatiques -
Partie 37: Méthode d'essai
de chute au niveau de la carte
avec utilisation d'un accéléromètre
(CEI 60749-37:2008)

Halbleiterbauelemente -
Mechanische und
klimatische Prüfverfahren -
Teil 37: Prüfverfahren Fall
der Leiterplatte unter Verwendung
eines Beschleunigungs-Messgerätes
(IEC 60749-37:2008)

This European Standard was approved by CENELEC on 2008-03-01. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the Central Secretariat has the same status as the official versions.

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CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: rue de Stassart 35, B - 1050 Brussels

I.S. EN 60749-37:2008

EN 60749-37:2008

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Foreword

The text of document 47/1937/FDIS, future edition 1 of IEC 60749-37, prepared by IEC TC 47, Semiconductor devices, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 60749-37 on 2008-03-01.

The following dates were fixed:

- | | | |
|--|-------|------------|
| – latest date by which the EN has to be implemented
at national level by publication of an identical
national standard or by endorsement | (dop) | 2008-12-01 |
| – latest date by which the national standards conflicting
with the EN have to be withdrawn | (dow) | 2011-03-01 |

Annex ZA has been added by CENELEC.

Endorsement notice

The text of the International Standard IEC 60749-37:2008 was approved by CENELEC as a European Standard without any modification.

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60749-10	2002	Semiconductor devices - Mechanical and climatic test methods - Part 10: Mechanical shock	EN 60749-10	2002
IEC 60749-20	- ¹⁾	Semiconductor devices - Mechanical and climatic test methods - Part 20: Resistance of plastic-encapsulated SMDs to the combined effect of moisture and soldering heat	EN 60749-20	2003 ²⁾
IEC 60749-20-1	- ³⁾	Semiconductor devices - Mechanical and climatic test methods - Part 20-1: Handling, packing, labelling and shipping of surface mount devices sensitive to the combined effect of moisture and soldering heat	-	-

¹⁾ Undated reference.

²⁾ Valid edition at date of issue.

³⁾ At draft stage.

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